

INTERCONNECT

ABSTRACT

An interconnect is described including a semiconductor substrate having opposing surfaces, including first and second insulated conductors for transmitting signals. A third conductor substantially surrounds and is electrically insulated from the first and second insulated conductors. Capacitance between the first insulated conductor and the third conductor is substantially equivalent to capacitance between the second insulated conductor and the third conductor. The first insulated conductor and the second insulated conductor are disposed between the opposing surfaces of the semiconductor substrate.